

Title (en)  
COMPONENTS WITH RELEASABLE LEADS

Title (de)  
BAUTEILEN MIT LÖSBAREN LEITERN

Title (fr)  
COMPOSANTS DOTES DE FILS DETACHABLES

Publication  
**EP 1059019 A4 20071017 (EN)**

Application  
**EP 99905891 A 19990209**

Priority  
• US 9902748 W 19990209  
• US 2075098 A 19980209  
• US 19537198 A 19981118  
• US 22566999 A 19990105

Abstract (en)  
[origin: WO9940761A1] A microelectronic component is made by providing a starting structure having a dielectric layer (22) and leads on a surface of the dielectric layer. The dielectric layer is etched to partially detach the leads (24) from the dielectric layer, leaving a portion of each lead releasably connected to the dielectric layer. Ends of the leads (24) may be connected to contacts (52) on a microelectronic element (50), such as the contacts on a semiconductor chip or wafer, before the dielectric layer (22) is etched to partially detach the leads (24) from the dielectric layer. The lead is partially detached from the dielectric layer so that the dielectric layer can be broken or peeled away from the leads during the step of moving the microelectronic element (50) and dielectric layer (22) away from one another.

IPC 1-7  
**H05K 3/30**; **H01R 9/09**

IPC 8 full level  
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Citation (search report)  
• [DX] WO 9403036 A1 19940203 - TESSERA INC [US], et al  
• [DA] US 5518964 A 19960521 - DISTEFANO THOMAS H [US], et al  
• [A] US 5086337 A 19920204 - NORO TAKANOBU [JP], et al  
• See references of WO 9940761A1

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